





# EMRE12J2H-100.000M

|   |   |  |   |
|---|---|--|---|
|  <b>Lead Free</b><br><br><b>COMPLIANT</b> |  <b>EU RoHS</b><br>2011/65 +<br>2015/863<br><b>COMPLIANT</b> |  <b>China RoHS</b><br><br><b>COMPLIANT</b> |  <b>REACH</b><br><b>SVHC 163</b><br>Jun 15, 2015<br><b>COMPLIANT</b> |
|---|---|--|---|



## ITEM DESCRIPTION

MEMS Clock Oscillators LVDS (DS) 2.5Vdc 6 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD) 100.000MHz  $\pm 25$ ppm over -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

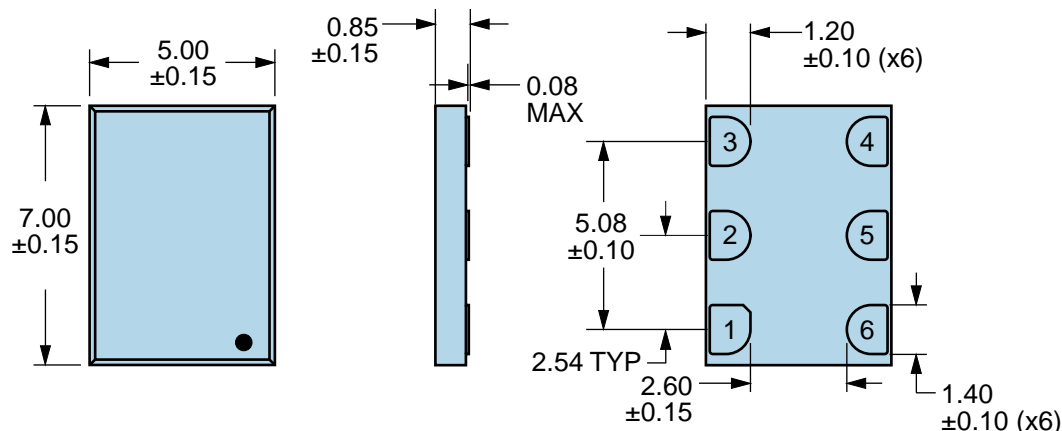
|  |  |
|--|--|
| <b>Nominal Frequency</b>                 | 100.000MHz   |
| <b>Frequency Tolerance/Stability</b>     | $\pm 25$ ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C, Reflow, Shock, and Vibration) |
| <b>Aging at 25°C</b>                     | $\pm 1$ ppm Maximum First Year   |
| <b>Supply Voltage</b>                    | 2.5Vdc $\pm 10\%$  |
| <b>Input Current</b>                     | 45mA Typical, 55mA Maximum (Excluding Load Termination Current)  |
| <b>Differential Output Error (dVod)</b>  | 50mVdc Maximum   |
| <b>Differential Output Voltage (Vod)</b> | 200mVdc Minimum, 350mVdc Typical, 500mVdc Maximum  |
| <b>Offset Voltage (Vos)</b>              | 1.125V Minimum, 1.20V Typical, 1.375V Maximum  |
| <b>Rise/Fall Time</b>                    | 500pSec Typical, 600pSec Maximum (Measured over 20% to 80% of waveform)  |
| <b>Duty Cycle</b>                        | 50 $\pm 5$ (%) (Measured at 50% of waveform)   |
| <b>Offset Error (dVos)</b>               | 50mVdc Maximum   |
| <b>Load Drive Capability</b>             | 100 Ohms Between Output and Complementary Output   |
| <b>Output Logic Type</b>                 | LVDS   |
| <b>Logic Control / Additional Output</b> | Output Enable (OE) and Complementary Output  |
| <b>Output Control Input Voltage</b>      | Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)   |
| <b>Output Enable Current</b>             | 35mA Maximum (OE) Without Load   |
| <b>RMS Phase Jitter</b>                  | 0.5pSec Typical, 1pSec Maximum (Fj = 12kHz to 20MHz; Random)   |
| <b>Period Jitter (Deterministic)</b>     | 0.2pSec Typical  |
| <b>Period Jitter (Random)</b>            | 1.0pSec Typical  |
| <b>Period Jitter (RMS)</b>               | 1.4pSec Typical, 1.7pSec Maximum   |
| <b>Period Jitter (pk-pk)</b>             | 15pSec Typical, 20pSec Maximum   |
| <b>Start Up Time</b>                     | 10mSec Maximum   |
| <b>Storage Temperature Range</b>         | -55°C to +125°C  |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                                     |   |
|-------------------------------------|---|
| <b>ESD Susceptibility</b>           | MIL-STD-883, Method 3015, Class 2, HBM 2000V                      |
| <b>Flammability</b>                 | UL94-V0   |
| <b>Mechanical Shock</b>             | MIL-STD-883, Method 2002, Condition G, 30,000G                    |
| <b>Moisture Resistance</b>          | MIL-STD-883, Method 1004  |
| <b>Moisture Sensitivity Level</b>   | J-STD-020, MSL 1  |
| <b>Resistance to Soldering Heat</b> | MIL-STD-202, Method 210, Condition K                              |
| <b>Resistance to Solvents</b>       | MIL-STD-202, Method 215   |
| <b>Solderability</b>                | MIL-STD-883, Method 2003 (Six I/O Pads on bottom of package only) |
| <b>Temperature Cycling</b>          | MIL-STD-883, Method 1010, Condition B                             |
| <b>Thermal Shock</b>                | MIL-STD-883, Method 1011, Condition B                             |
| <b>Vibration</b>                    | MIL-STD-883, Method 2007, Condition A, 20G                        |

# EMRE12J2H-100.000M

## MECHANICAL DIMENSIONS (all dimensions in millimeters)

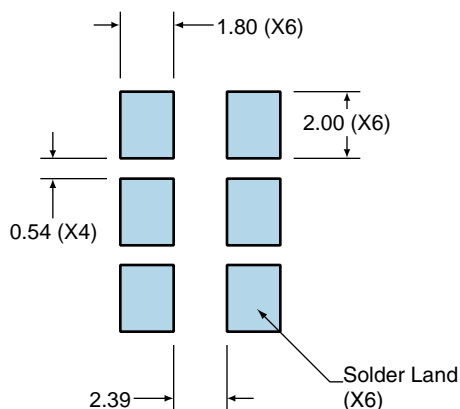


| PIN | CONNECTION           |
|-----|----------------------|
| 1   | Output Enable (OE)   |
| 2   | No Connect           |
| 3   | Case Ground          |
| 4   | Output               |
| 5   | Complementary Output |
| 6   | Supply Voltage       |

| LINE | MARKING   |
|------|---|
| 1    | XXXXXX<br>XXXXXX=Ecliptek<br>Manufacturing Lot Code |

## Suggested Solder Pad Layout

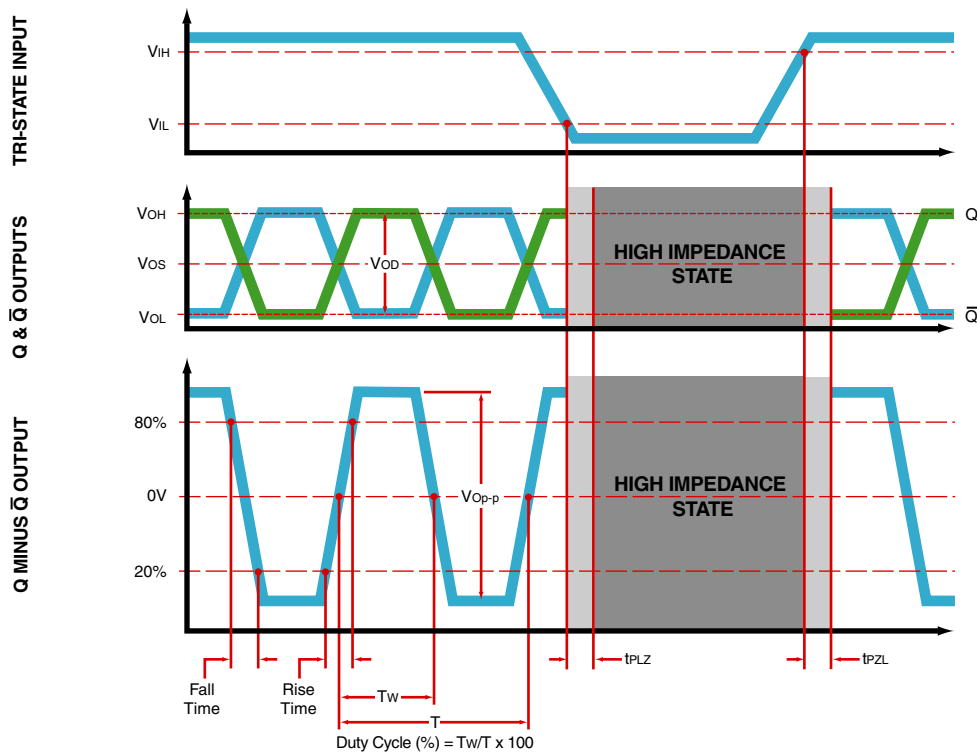
All Dimensions in Millimeters



All Tolerances are ±0.1

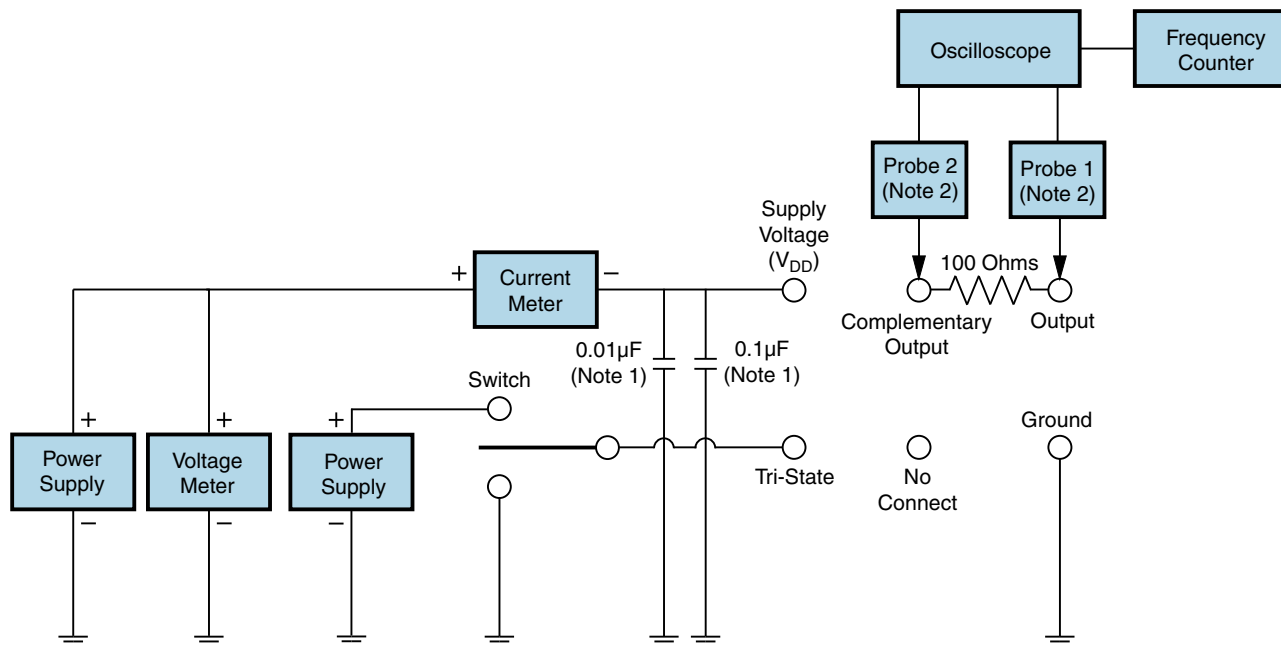
# EMRE12J2H-100.000M

## OUTPUT WAVEFORM & TIMING DIAGRAM



# EMRE12J2H-100.000M

## Test Circuit for Tri-State and Complementary Output



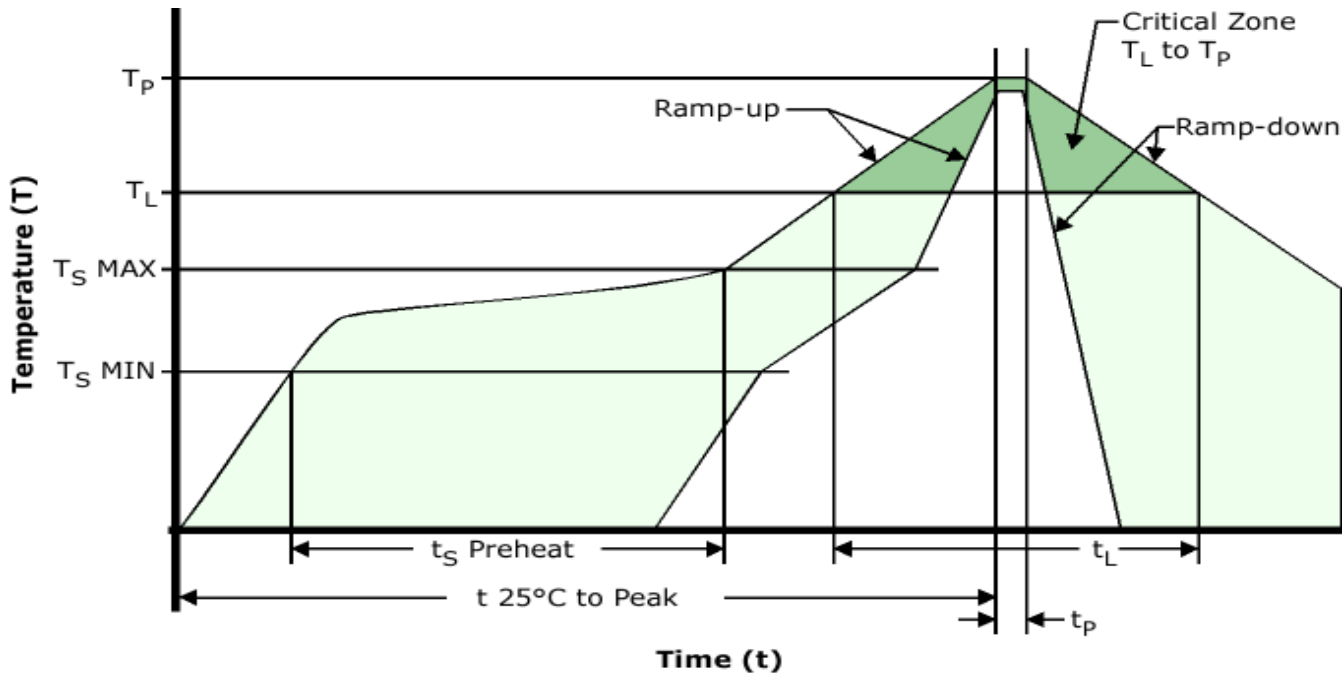
Note 1: An external  $0.01\mu\text{F}$  ceramic bypass capacitor in parallel with a  $0.1\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>500\text{MHz}$ ) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

# EMRE12J2H-100.000M

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

$T_S$  MAX to  $T_L$  (Ramp-up Rate) 3°C/Second Maximum

#### Preheat

- Temperature Minimum ( $T_S$  MIN) 150°C
- Temperature Typical ( $T_S$  TYP) 175°C
- Temperature Maximum ( $T_S$  MAX) 200°C
- Time ( $t_s$  MIN) 60 - 180 Seconds

Ramp-up Rate ( $T_L$  to  $T_P$ ) 3°C/Second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 217°C
- Time ( $t_L$ ) 60 - 150 Seconds

Peak Temperature ( $T_P$ ) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature ( $T_P$  Target) 250°C +0/-5°C

Time within 5°C of actual peak ( $t_p$ ) 20 - 40 Seconds

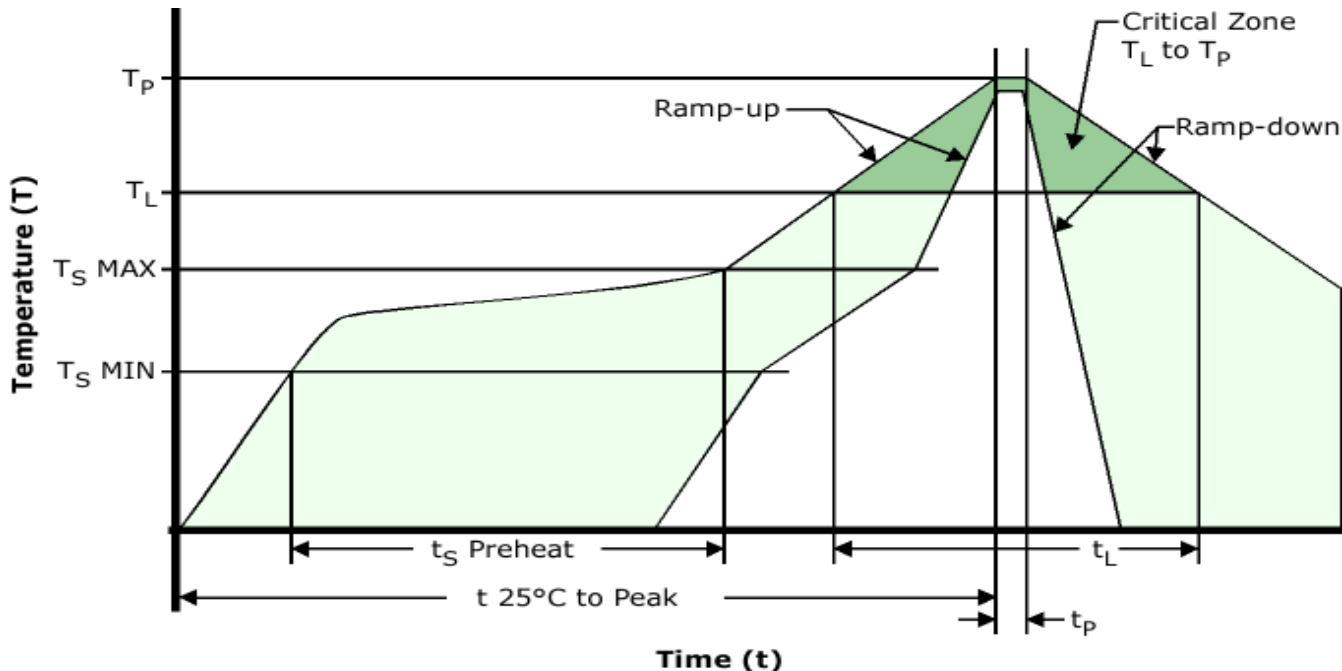
Ramp-down Rate 6°C/Second Maximum

Time 25°C to Peak Temperature (t) 8 Minutes Maximum

Moisture Sensitivity Level Level 1

# EMRE12J2H-100.000M

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

$T_S$  MAX to  $T_L$  (Ramp-up Rate) 5°C/Second Maximum

#### Preheat

- Temperature Minimum ( $T_S$  MIN) N/A  
 - Temperature Typical ( $T_S$  TYP) 150°C  
 - Temperature Maximum ( $T_S$  MAX) N/A  
 - Time ( $t_s$  MIN) 60 - 120 Seconds

Ramp-up Rate ( $T_L$  to  $T_P$ ) 5°C/Second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 150°C  
 - Time ( $t_L$ ) 200 Seconds Maximum

Peak Temperature ( $T_P$ ) 240°C Maximum

Target Peak Temperature ( $T_P$  Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak ( $t_p$ ) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.

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